

Appl. No. 10/659,883
Amdt. dated February 22, 2006
Reply to Office action of November 23, 2005

In the Claims:

Claims 1 and 5 are amended herein. The remaining claims are not amended in this response.

1. (currently amended) A method for fabricating a ceramic board with high integration of multi-polyimide-layer DPC lines, comprising the following steps:

defining fine through holes on a portion of a ceramic board;

forming conductive pillars in the fine through holes ~~by~~ and
made of a conductive material;

forming first metal lines on an upper surface and a bottom surface of the ceramic board, wherein the conductive pillars connect with the first metal lines respectively formed on the upper surface and the bottom surface of the ceramic board;

applying an insulating layer on the upper surface and the bottom surface of the ceramic board to cover the upper surface and the bottom surface of the ceramic board and the first metal lines; and

forming second metal lines in the insulating layer, wherein when using conductive material to form the second metal lines.

2. (original) The method as claimed in claim 1, wherein the method further comprises an electronically connecting step after the applying insulating layer step, wherein the electronically connecting step is forming columns in the

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insulating layer for electronically connecting the first metal lines with the second metal lines.

3. (original) The method as claimed in claim 1, wherein the fine through holes defined in the ceramic board are cut by using laser beams.

4. (original) The method as claimed in claim 1, wherein the fine through holes defined in the ceramic board are cut by using a photolithography technology.

5. (currently amended) The method as claimed in claim 1, wherein the conductive material of the conductive pillars is copper ~~or silver~~ material.

6. (original) The method as claimed in claim 1, wherein the conductive material of the conductive pillars is silver material.

7. (original) The method as claimed in claim 1, wherein the conductive material of the first and second metal lines is titanium.

8. (original) The method as claimed in claim 1, wherein the conductive material of the first and second metal lines is copper material.